

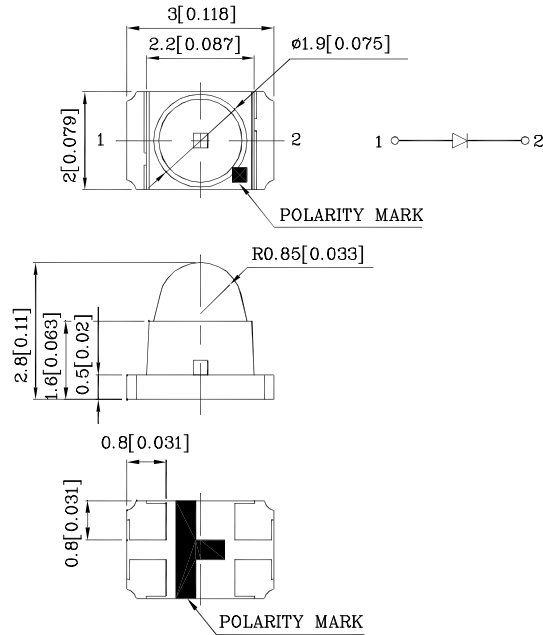
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Tinned pads for improved solderability
- Package : 2000pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



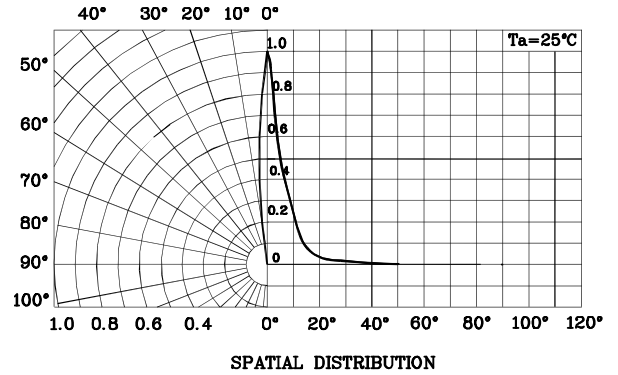
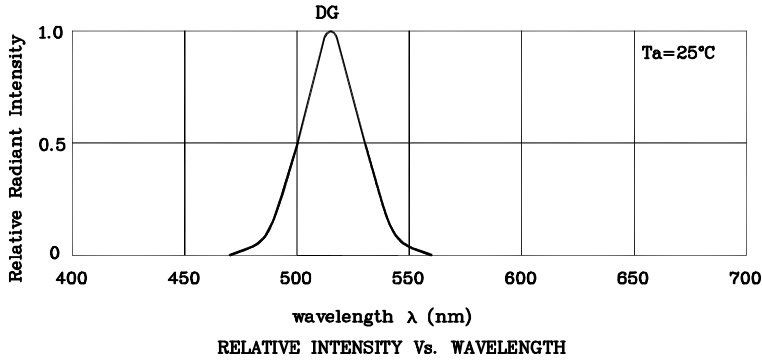
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.

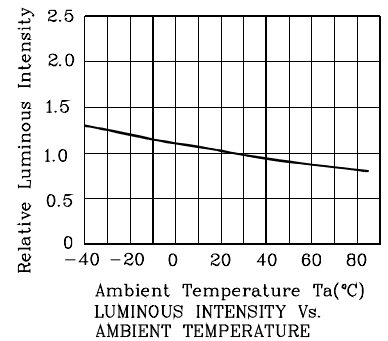
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		DG (InGaN)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	150	mA
Power Dissipation	P_D	102.5	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		450	V

Operating Characteristics ($T_A=25^\circ\text{C}$)		DG (InGaN)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	3.3	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	4.1	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	50	μA
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	515	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZDG50WT-2	Green	InGaN	Water Clear	900	1495	515	10°



❖ DG



LED is recommended for reflow soldering and soldering profile is shown below.

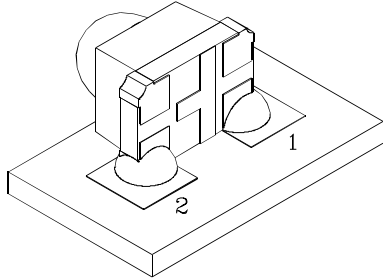
Reflow Soldering Profile for SMD Products (Pb-Free Components)



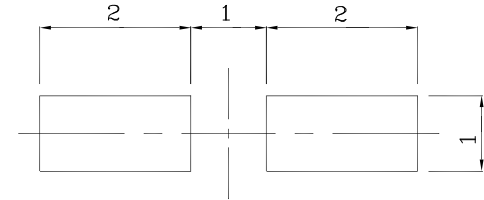
- Notes:
1. Maximum soldering temperature should not exceed 280°C
 2. Recommended reflow temperature: 145°C-280°C
 3. Do not put stress to the epoxy resin during high temperatures conditions



❖ The device has a single mounting surface.
The device must be mounted according to the specifications.



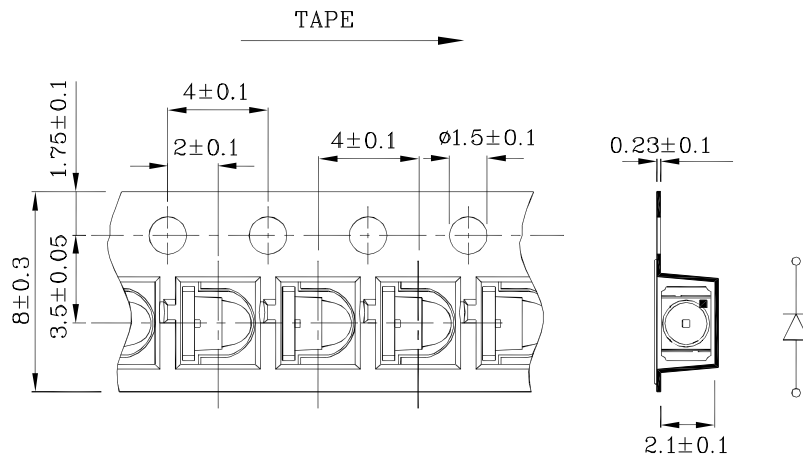
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units : mm)



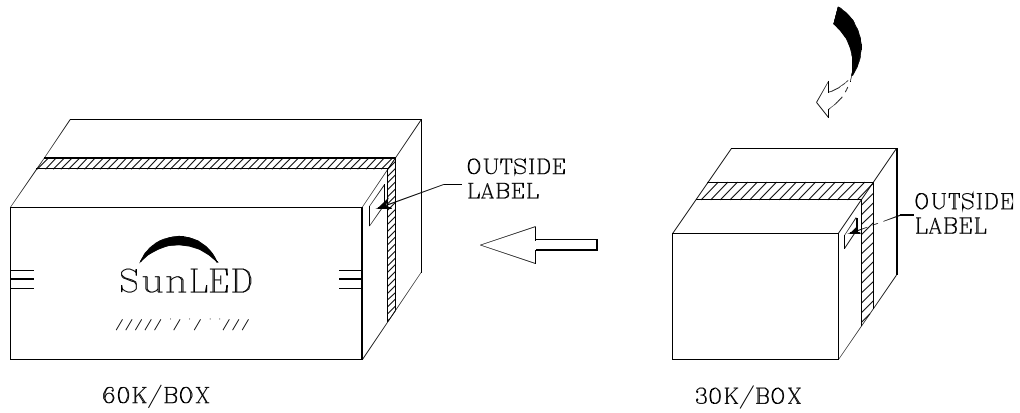
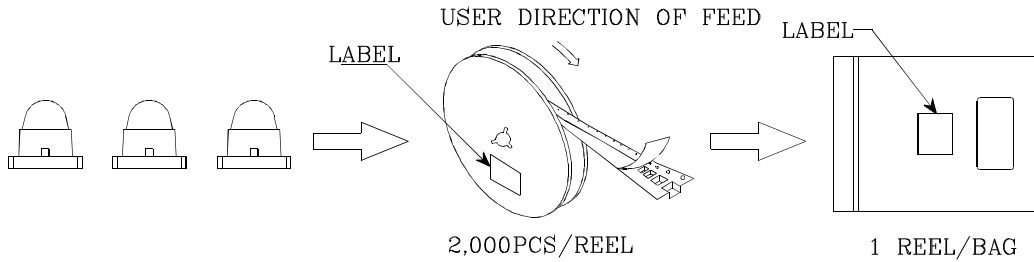

Remarks:

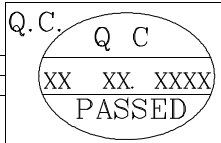

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS


P/NO : XZxxx50x
QTY : 2,000 pcs CODE: XXX
S/N : XX
LOT NO :
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX
RoHS Compliant